PATENT ABSTRACTS OF JAPAN

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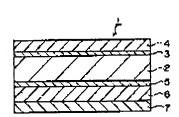
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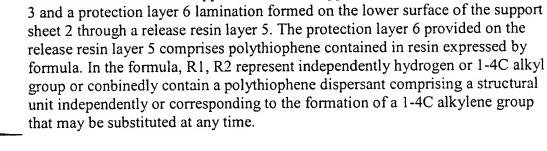
(54) THERMAL TRANSFER SHEET AND IC CARD EMPLOYING THE SAME

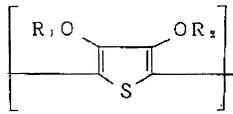


(57) Abstract:

PROBLEM TO BE SOLVED: To enable a signal communication with external connection terminals even in the formation of a protection layer on the electrode surface of an IC card giving the protection layer conductivity by adding in the protection layer a polythiophene of a specific formula in the presence of a polyanion.

SOLUTION: The thermal transfer sheet 1 includes a heat resistance slide layer lamination formed on the upper surface of a support sheet 2 through a primer layer





LEGAL STATUS

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